

P-Channel Trench Power MOSFET

General Description

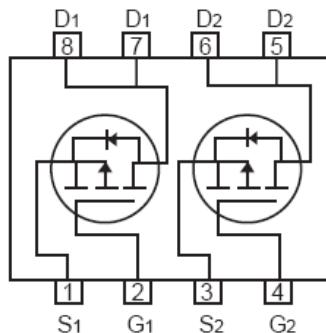
The CS4953 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a load switch or in PWM applications.

Features

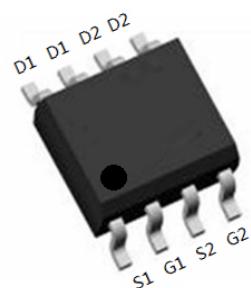
- $V_{DS} = -30V, I_D = -5.1A$
- $R_{DS(ON)} < 49m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} < 100m\Omega @ V_{GS} = -4.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

Application

- PWM applications
- Load switch
- Power management



Schematic Diagram



SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
CS4953	CS4953	SOP-8	Ø330mm	12mm	2500 units

Table 1. Absolute Maximum Ratings ($T_A=25^\circ C$)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	-30	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
I_D	Drain Current-Continuous	-5.1	A
I_{DM} (pulse)	Drain Current-Continuous@ Current-Pulsed <small>(Note 1)</small>	-30	A
P_D	Maximum Power Dissipation	2.5	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	°C

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

Table 2. Thermal Characteristic

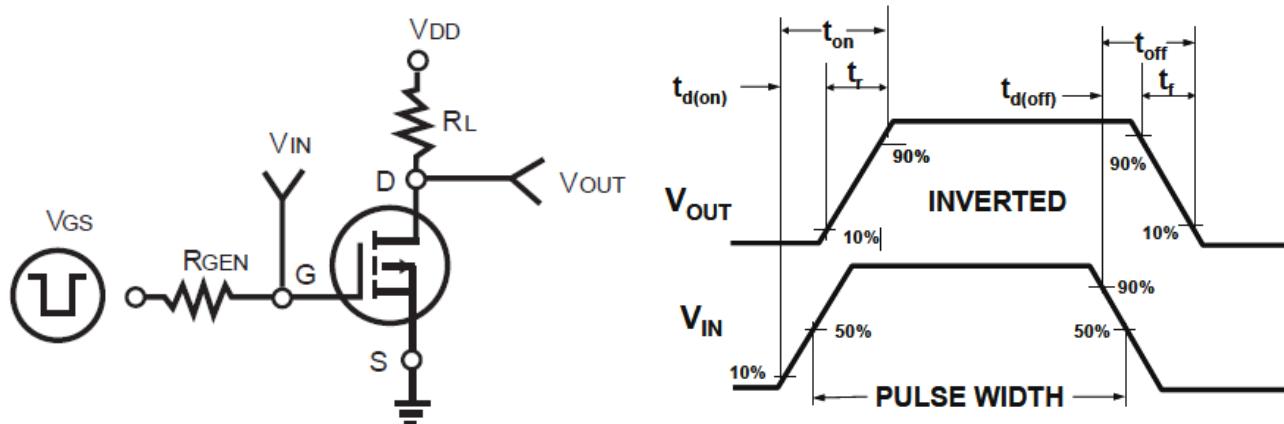
Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	°C/W

Table 3. Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250\mu\text{A}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-24\text{V}, V_{GS}=0\text{V}$			-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$			± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1	-1.6	-3	V
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}, I_D=-4.5\text{A}$	4			S
$R_{DS(\text{ON})}$	Drain-Source On-State Resistance	$V_{GS}=-10\text{V}, I_D=-5.1\text{A}$		38	49	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}, I_D=-4.2\text{A}$		61	100	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$		630		pF
C_{oss}	Output Capacitance			130		pF
C_{rss}	Reverse Transfer Capacitance			95		pF
Switching Times						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-15\text{V}, I_D=-1\text{A}, R_L=15\Omega, V_{GS}=-10\text{V}, R_G=2.5\Omega$		11		nS
t_r	Turn-on Rise Time			5		nS
$t_{d(off)}$	Turn-Off Delay Time			30		nS
t_f	Turn-Off Fall Time			7		nS
Q_g	Total Gate Charge	$V_{DS}=-15\text{V}, I_D=-4.9\text{A}, V_{GS}=-10\text{V}$		13		nC
Q_{gs}	Gate-Source Charge			2.5		nC
Q_{gd}	Gate-Drain Charge			3		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current(Body Diode)				-1.7	A
V_{SD}	Forward on Voltage ^(Note 1)	$V_{GS}=0\text{V}, I_S=-1.7\text{A}$			-1.2	V

Notes 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Switch Time Test Circuit and Switching Waveforms:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. Power Dissipation

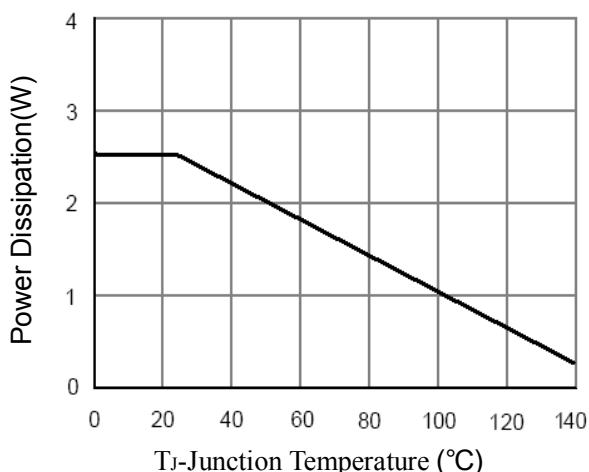


Figure2. Drain Current

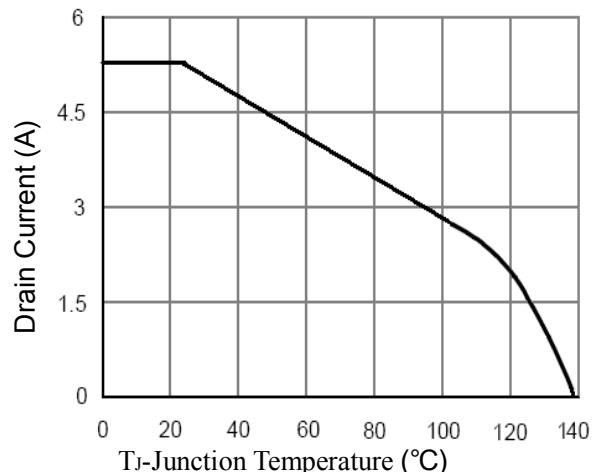


Figure3. Output Characteristics

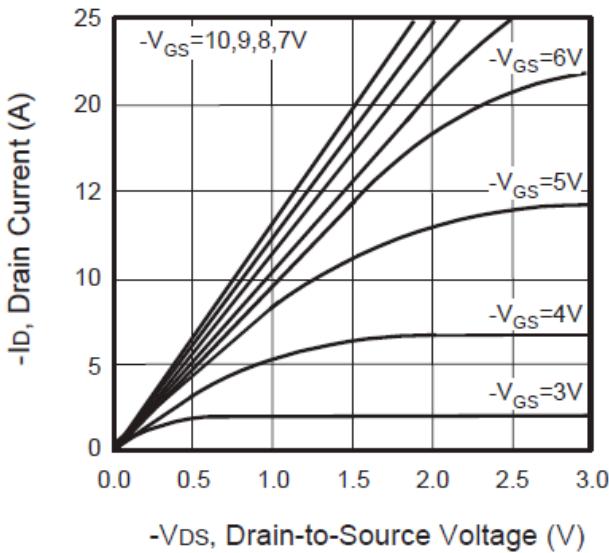


Figure4. Transfer Characteristics

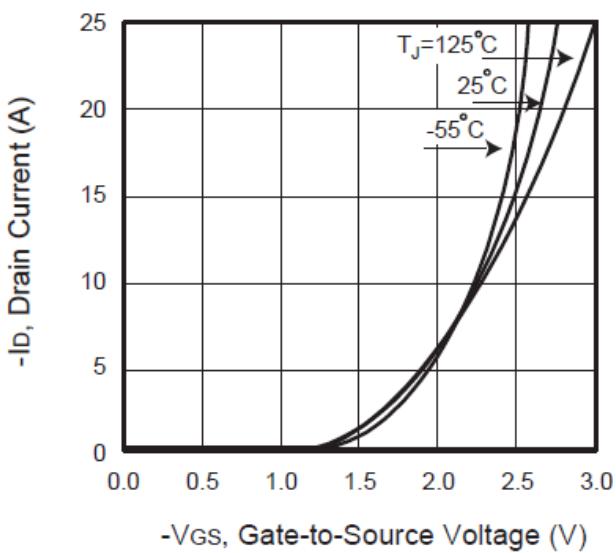


Figure5. Capacitance

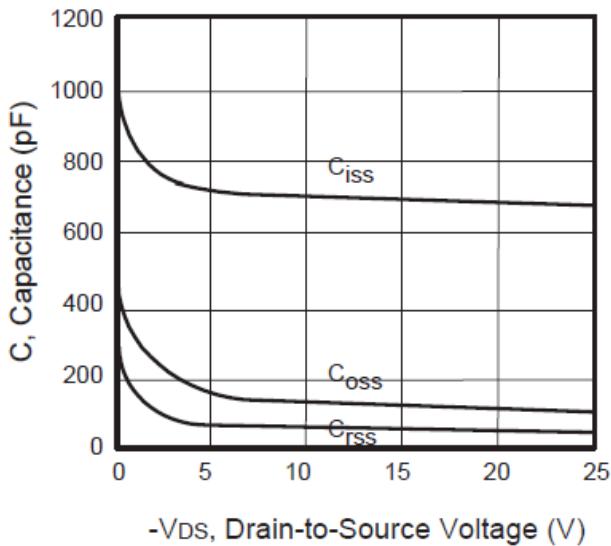


Figure6. R_{DS(ON)} vs Junction Temperature

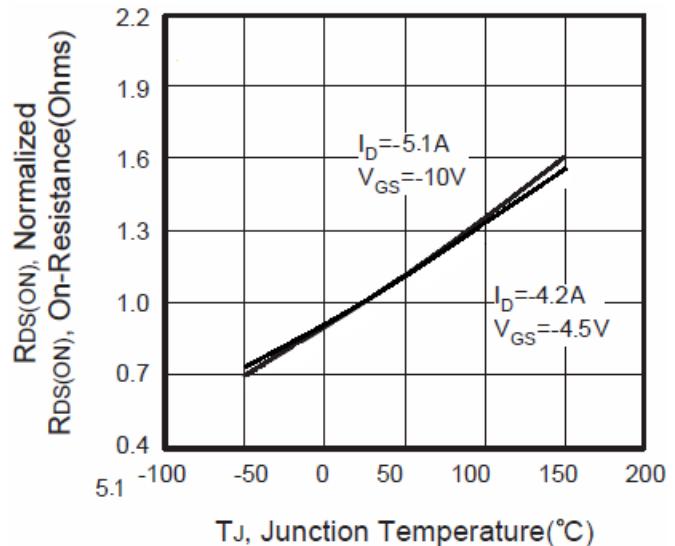


Figure7. MaxBV_{DSS} vs Junction Temperature

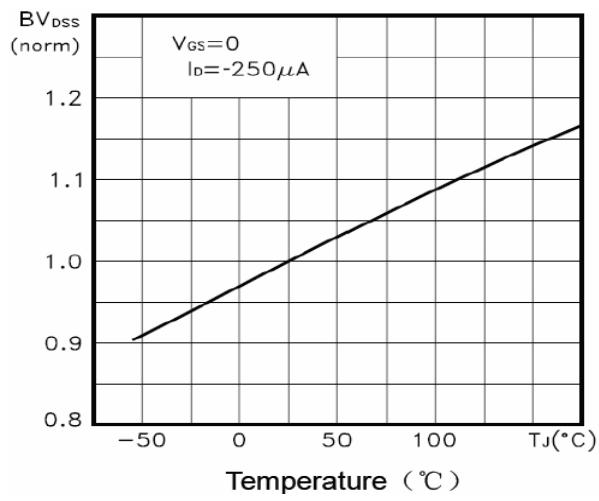


Figure8. V_{GS(th)} vs Junction Temperature

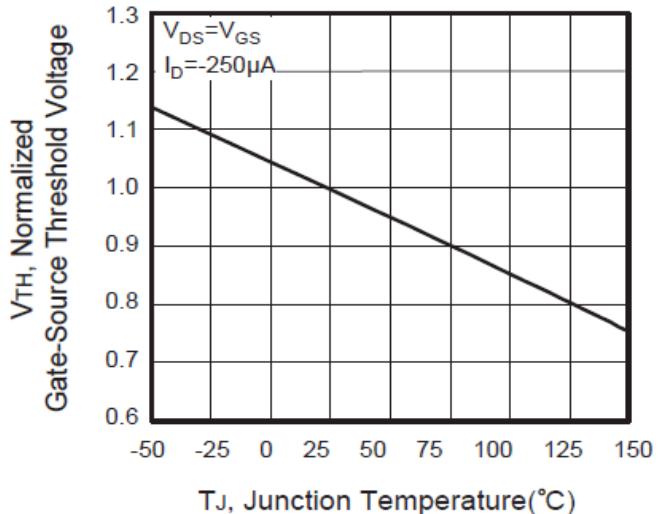


Figure9. Gate Charge Waveforms

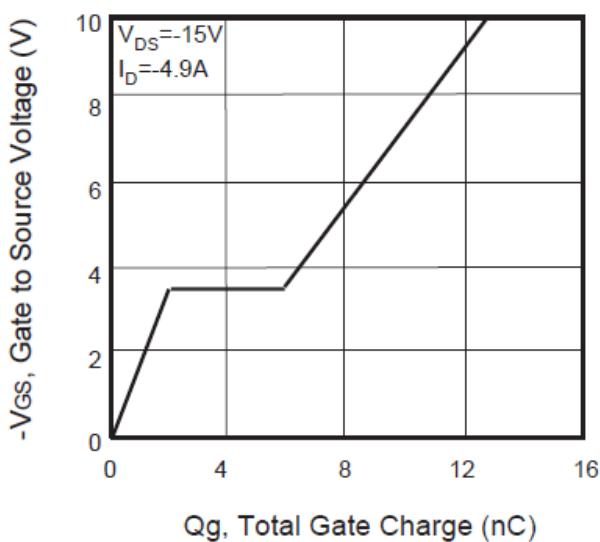


Figure10. Maximum Safe Operating Area

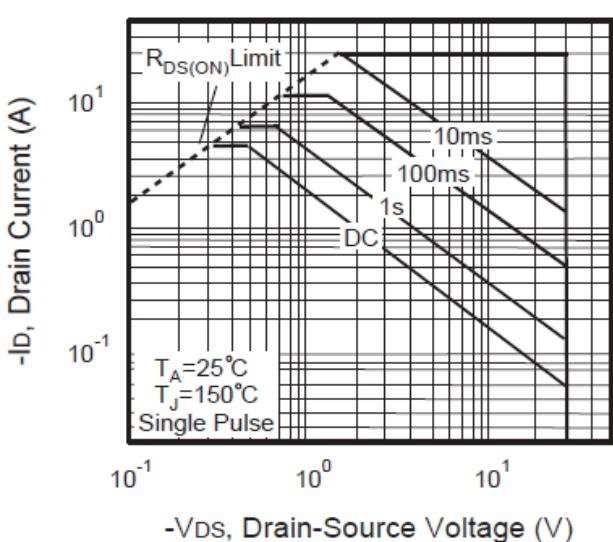
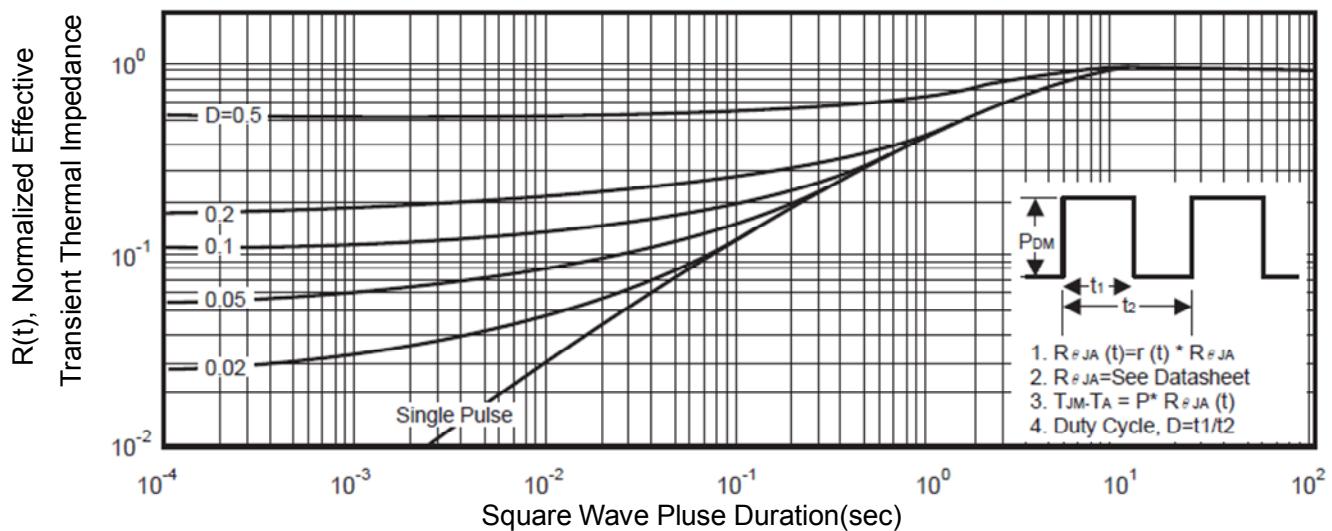


Figure11. Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information

